



Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	359200
Number of Logic Elements/Cells	952000
Total RAM Bits	53248000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1760-BBGA, FCBGA
Supplier Device Package	1760-HBGA (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxebbr2h43i2

Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering ^{(1), (2), (3)} (Part 2 of 2)

Transceiver Speed Grade	Core Speed Grade							
	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L	I3YY	I4
3 GX channel—8.5 Gbps	—	Yes	Yes	Yes	—	Yes	Yes ⁽⁴⁾	Yes

Notes to Table 1:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
 (2) Lower number refers to faster speed grade.
 (3) C2L, I2L, and I3L speed grades are for low-power devices.
 (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering ^{(1), (2)}

Transceiver Speed Grade	Core Speed Grade			
	C1	C2	I2	I3
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	—	—
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes

Notes to Table 2:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
 (2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)

Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Power supply for core voltage and periphery circuitry	−0.5	1.35	V
V _{CCPT}	Power supply for programmable power technology	−0.5	1.8	V
V _{CCPGM}	Power supply for configuration pins	−0.5	3.9	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	−0.5	3.4	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	−0.5	3.9	V
V _{CCPD}	I/O pre-driver power supply	−0.5	3.9	V
V _{CCIO}	I/O power supply	−0.5	3.9	V

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 2 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Typ	Max ⁽⁴⁾	Unit
t _{RAMP}	Power supply ramp time	Standard POR	200 μ s	—	100 ms	—
		Fast POR	200 μ s	—	4 ms	—

Notes to Table 6:

- (1) V_{CCPD} must be 2.5 V when V_{CCIO} is 2.5, 1.8, 1.5, 1.35, 1.25 or 1.2 V. V_{CCPD} must be 3.0 V when V_{CCIO} is 3.0 V.
- (2) If you do not use the design security feature in Stratix V devices, connect V_{CCBAT} to a 1.2- to 3.0-V power supply. Stratix V power-on-reset (POR) circuitry monitors V_{CCBAT}. Stratix V devices will not exit POR if V_{CCBAT} stays at logic low.
- (3) C2L and I2L can also be run at 0.90 V for legacy boards that were designed for the C2 and I2 speed grades.
- (4) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 7 lists the transceiver power supply recommended operating conditions for Stratix V GX, GS, and GT devices.

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 1 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
V _{CCA_GXBL} (1), (3)	Transceiver channel PLL power supply (left side)	GX, GS, GT	2.85	3.0	3.15	V
			2.375	2.5	2.625	
V _{CCA_GXBR} (1), (3)	Transceiver channel PLL power supply (right side)	GX, GS	2.85	3.0	3.15	V
			2.375	2.5	2.625	
V _{CCA_GTBR}	Transceiver channel PLL power supply (right side)	GT	2.85	3.0	3.15	V
V _{CCHIP_L}	Transceiver hard IP power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver hard IP power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V _{CCHIP_R}	Transceiver hard IP power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver hard IP power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V _{CCHSSI_L}	Transceiver PCS power supply (left side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver PCS power supply (left side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V _{CCHSSI_R}	Transceiver PCS power supply (right side; C1, C2, I2, and I3YY speed grades)	GX, GS, GT	0.87	0.9	0.93	V
	Transceiver PCS power supply (right side; C2L, C3, C4, I2L, I3, I3L, and I4 speed grades)	GX, GS, GT	0.82	0.85	0.88	V
V _{CCR_GXBL} (2)	Receiver analog power supply (left side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	

Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)

Symbol	Description	Devices	Minimum ⁽⁴⁾	Typical	Maximum ⁽⁴⁾	Unit
V_{CCR_GXBR} (2)	Receiver analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
V_{CCR_GTBR}	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V_{CCT_GXBL} (2)	Transmitter analog power supply (left side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
V_{CCT_GXBR} (2)	Transmitter analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
V_{CCT_GTBR}	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
V_{CCL_GTBR}	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
V_{CCH_GXBL}	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
V_{CCH_GXBR}	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

Notes to Table 7:

- (1) This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.
- (2) Refer to Table 8 to select the correct power supply level for your design.
- (3) When using ATX PLLs, the supply must be 3.0 V.
- (4) This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

Table 9. I/O Pin Leakage Current for Stratix V Devices ⁽¹⁾

Symbol	Description	Conditions	Min	Typ	Max	Unit
I_I	Input pin	$V_I = 0 \text{ V to } V_{CCIOMAX}$	-30	—	30	μA
I_{OZ}	Tri-stated I/O pin	$V_O = 0 \text{ V to } V_{CCIOMAX}$	-30	—	30	μA

Note to Table 9:

(1) If $V_O = V_{CCIO}$ to $V_{CCIOMAX}$, 100 μA of leakage current per I/O is expected.

Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

Table 10. Bus Hold Parameters for Stratix V Devices

Parameter	Symbol	Conditions	V _{CCIO}										Unit
			1.2 V		1.5 V		1.8 V		2.5 V		3.0 V		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I _{SUSL}	V _{IN} > V _{IL} (maximum)	22.5	—	25.0	—	30.0	—	50.0	—	70.0	—	μA
High sustaining current	I _{SUSH}	V _{IN} < V _{IH} (minimum)	−22.5	—	−25.0	—	−30.0	—	−50.0	—	−70.0	—	μA
Low overdrive current	I _{ODL}	0V < V _{IN} < V _{CCIO}	—	120	—	160	—	200	—	300	—	500	μA
High overdrive current	I _{ODH}	0V < V _{IN} < V _{CCIO}	—	−120	—	−160	—	−200	—	−300	—	−500	μA
Bus-hold trip point	V _{TRIP}	—	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices ⁽¹⁾ (Part 1 of 2)

Symbol	Description	Conditions	Calibration Accuracy				Unit
			C1	C2,I2	C3,I3, I3YY	C4,I4	
25- Ω R_S	Internal series termination with calibration (25- Ω setting)	$V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 \text{ V}$	± 15	± 15	± 15	± 15	%

Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices ⁽¹⁾ (Part 2 of 2)

Symbol	Description	Conditions	Calibration Accuracy				Unit
			C1	C2,I2	C3,I3,I3YY	C4,I4	
50-Ω R _S	Internal series termination with calibration (50-Ω setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
34-Ω and 40-Ω R _S	Internal series termination with calibration (34-Ω and 40-Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
48-Ω, 60-Ω, 80-Ω, and 240-Ω R _S	Internal series termination with calibration (48-Ω, 60-Ω, 80-Ω, and 240-Ω setting)	V _{CCIO} = 1.2 V	±15	±15	±15	±15	%
50-Ω R _T	Internal parallel termination with calibration (50-Ω setting)	V _{CCIO} = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω R _T	Internal parallel termination with calibration (20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
60-Ω and 120-Ω R _T	Internal parallel termination with calibration (60-Ω and 120-Ω setting)	V _{CCIO} = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
25-Ω R _{S_left_shift}	Internal left shift series termination with calibration (25-Ω R _{S_left_shift} setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

Note to Table 11:

(1) OCT calibration accuracy is valid at the time of calibration only.

Table 12 lists the Stratix V OCT without calibration resistance tolerance to PVT changes.

Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 1 of 2)

Symbol	Description	Conditions	Resistance Tolerance				Unit
			C1	C2,I2	C3, I3, I3YY	C4, I4	
25-Ω R, 50-Ω R _S	Internal series termination without calibration (25-Ω setting)	V _{CCIO} = 3.0 and 2.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	V _{CCIO} = 1.8 and 1.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25-Ω setting)	V _{CCIO} = 1.2 V	±35	±35	±50	±50	%



-
-  You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.
-  For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices ⁽¹⁾ (Part 3 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Reconfiguration clock (<i>mgmt_clk_clk</i>) frequency	—	100	—	125	100	—	125	100	—	125	MHz
Receiver											
Supported I/O Standards	—	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS									
Data rate (Standard PCS) ^{(9), (23)}	—	600	—	12200	600	—	12200	600	—	8500/ 10312.5 ⁽²⁴⁾	Mbps
Data rate (10G PCS) ^{(9), (23)}	—	600	—	14100	600	—	12500	600	—	8500/ 10312.5 ⁽²⁴⁾	Mbps
Absolute V_{MAX} for a receiver pin ⁽⁵⁾	—	—	—	1.2	—	—	1.2	—	—	1.2	V
Absolute V_{MIN} for a receiver pin	—	−0.4	—	—	−0.4	—	—	−0.4	—	—	V
Maximum peak- to-peak differential input voltage V_{ID} (diff p- p) before device configuration ⁽²²⁾	—	—	—	1.6	—	—	1.6	—	—	1.6	V
Maximum peak- to-peak differential input voltage V_{ID} (diff p- p) after device configuration ^{(18), (22)}	$V_{CCR_GXB} = 1.0\text{ V}/1.05\text{ V}$ ($V_{ICM} = 0.70\text{ V}$)	—	—	2.0	—	—	2.0	—	—	2.0	V
	$V_{CCR_GXB} = 0.90\text{ V}$ ($V_{ICM} = 0.6\text{ V}$)	—	—	2.4	—	—	2.4	—	—	2.4	V
	$V_{CCR_GXB} = 0.85\text{ V}$ ($V_{ICM} = 0.6\text{ V}$)	—	—	2.4	—	—	2.4	—	—	2.4	V
Minimum differential eye opening at receiver serial input pins ^{(6), (22), (27)}	—	85	—	—	85	—	—	85	—	—	mV

Table 27 shows the V_{OD} settings for the GX channel.

Table 27. Typical V_{OD} Setting for GX Channel, TX Termination = 100 Ω ⁽²⁾

Symbol	V_{OD} Setting	V_{OD} Value (mV)	V_{OD} Setting	V_{OD} Value (mV)
V_{OD} differential peak to peak typical ⁽³⁾	0 ⁽¹⁾	0	32	640
	1 ⁽¹⁾	20	33	660
	2 ⁽¹⁾	40	34	680
	3 ⁽¹⁾	60	35	700
	4 ⁽¹⁾	80	36	720
	5 ⁽¹⁾	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
	15	300	47	940
	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

Note to Table 27:

- (1) If TX termination resistance = 100 Ω , this VOD setting is illegal.
- (2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.
- (3) Refer to Figure 2.

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5) ⁽¹⁾

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Differential on-chip termination resistors ⁽⁷⁾	GT channels	—	100	—	—	100	—	Ω
Differential on-chip termination resistors for GX channels ⁽¹⁹⁾	85- Ω setting	—	85 \pm 30%	—	—	85 \pm 30%	—	Ω
	100- Ω setting	—	100 \pm 30%	—	—	100 \pm 30%	—	Ω
	120- Ω setting	—	120 \pm 30%	—	—	120 \pm 30%	—	Ω
	150- Ω setting	—	150 \pm 30%	—	—	150 \pm 30%	—	Ω
V _{ICM} (AC coupled)	GT channels	—	650	—	—	650	—	mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 0.85 V or 0.9 V	—	600	—	—	600	—	mV
	VCCR_GXB = 1.0 V full bandwidth	—	700	—	—	700	—	mV
	VCCR_GXB = 1.0 V half bandwidth	—	750	—	—	750	—	mV
t _{LTR} ⁽⁹⁾	—	—	—	10	—	—	10	μ s
t _{LTD} ⁽¹⁰⁾	—	4	—	—	4	—	—	μ s
t _{LTD_manual} ⁽¹¹⁾	—	4	—	—	4	—	—	μ s
t _{LTR_LTD_manual} ⁽¹²⁾	—	15	—	—	15	—	—	μ s
Run Length	GT channels	—	—	72	—	—	72	CID
	GX channels	⁽⁸⁾						
CDR PPM	GT channels	—	—	1000	—	—	1000	\pm PPM
	GX channels	⁽⁸⁾						
Programmable equalization (AC Gain) ⁽⁵⁾	GT channels	—	—	14	—	—	14	dB
	GX channels	⁽⁸⁾						
Programmable DC gain ⁽⁶⁾	GT channels	—	—	7.5	—	—	7.5	dB
	GX channels	⁽⁸⁾						
Differential on-chip termination resistors ⁽⁷⁾	GT channels	—	100	—	—	100	—	Ω
Transmitter								
Supported I/O Standards	—	1.4-V and 1.5-V PCML						
Data rate (Standard PCS)	GX channels	600	—	8500	600	—	8500	Mbps
Data rate (10G PCS)	GX channels	600	—	12,500	600	—	12,500	Mbps

Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 of 5) ⁽¹⁾

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
t_{pll_lock} ⁽¹⁴⁾	—	—	—	10	—	—	10	μs

Notes to Table 28:

- (1) Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the VCCR_GXB power supply level.
- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The differential eye opening specification at the receiver input pins assumes that receiver equalization is disabled. If you enable receiver equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (5) Refer to Figure 5 for the GT channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (6) Refer to Figure 6 for the GT channel DC gain curves.
- (7) CFP2 optical modules require the host interface to have the receiver data pins differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (8) Specifications for this parameter are the same as for Stratix V GX and GS devices. See Table 23 for specifications.
- (9) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (10) t_{LTD} is time required for the receiver CDR to start recovering valid data after the $rx_is_lockedto\ data$ signal goes high.
- (11) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the $rx_is_lockedto\ data$ signal goes high when the CDR is functioning in the manual mode.
- (12) $t_{LTR_LTD_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the $rx_is_lockedto\ ref$ signal goes high when the CDR is functioning in the manual mode.
- (13) $tp11_powerdown$ is the PLL powerdown minimum pulse width.
- (14) $tp11_lock$ is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (15) To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula:
REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (16) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to $4 \times (\text{absolute } V_{MAX} \text{ for receiver pin} - V_{ICM})$.
- (17) For ES devices, RREF is 2000 Ω ±1%.
- (18) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (19) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (20) Refer to Figure 4.
- (21) For oversampling design to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (22) This supply follows VCCR_GXB for both GX and GT channels.
- (23) When you use fPLL as a TXPLL of the transceiver.

Table 33. Memory Block Performance Specifications for Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Memory	Mode	Resources Used		Performance							Unit
		ALUTs	Memory	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L, I3YY	I4	
M20K Block	Single-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	525	525	455	400	525	455	400	MHz
	Simple dual-port with ECC enabled, 512 × 32	0	1	450	450	400	350	450	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	600	600	500	450	600	500	450	MHz
	True dual port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	ROM, all supported widths	0	1	700	700	650	550	700	500	450	MHz

Notes to Table 33:

- (1) To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.
- (2) When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F_{MAX}.
- (3) The F_{MAX} specification is only achievable with Fitter options, **MLAB Implementation In 16-Bit Deep Mode** enabled.

Temperature Sensing Diode Specifications

Table 34 lists the internal TSD specification.

Table 34. Internal Temperature Sensing Diode Specification

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
–40°C to 100°C	±8°C	No	1 MHz, 500 KHz	< 100 ms	8 bits	8 bits

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

Table 35. External Temperature Sensing Diode Specifications for Stratix V Devices

Description	Min	Typ	Max	Unit
I _{bias} , diode source current	8	—	200	μA
V _{bias} , voltage across diode	0.3	—	0.9	V
Series resistance	—	—	< 1	Ω
Diode ideality factor	1.006	1.008	1.010	—

Table 36. High-Speed I/O Specifications for Stratix V Devices ⁽¹⁾, ⁽²⁾ (Part 2 of 4)

Symbol	Conditions	C1			C2, C2L, I2, I2L			C3, I3, I3L, I3YY			C4,I4			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Transmitter														
True Differential I/O Standards - f _{HSDR} (data rate)	SERDES factor J = 3 to 10 ^{(9), (11), (12), (13), (14), (15), (16)}	(6)	—	1600	(6)	—	1434	(6)	—	1250	(6)	—	1050	Mbps
	SERDES factor J ≥ 4 LVDS TX with DPA ^{(12), (14), (15), (16)}	(6)	—	1600	(6)	—	1600	(6)	—	1600	(6)	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	(6)	—	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f _{HSDR} (data rate) ⁽¹⁰⁾	SERDES factor J = 4 to 10 ⁽¹⁷⁾	(6)	—	1100	(6)	—	1100	(6)	—	840	(6)	—	840	Mbps
t _{x Jitter} - True Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	—	—	160	—	—	160	—	—	160	—	—	160	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.1	—	—	0.1	—	—	0.1	—	—	0.1	UI
t _{x Jitter} - Emulated Differential I/O Standards with Three External Output Resistor Network	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	—	—	300	—	—	300	—	—	300	—	—	325	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.2	—	—	0.2	—	—	0.2	—	—	0.25	UI

Table 38. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate ≥ 1.25 Gbps

Jitter Frequency (Hz)		Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

Figure 9 shows the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate < 1.25 Gbps.

Figure 9. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate < 1.25 Gbps

DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

Table 39. DLL Range Specifications for Stratix V Devices ⁽¹⁾

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

Note to Table 39:

- (1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices ^{(1), (2)} (Part 1 of 2)

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

Table 49. DCLK-to-DATA[] Ratio ⁽¹⁾ (Part 2 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
FPP ×32	Disabled	Disabled	1
	Disabled	Enabled	4
	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

- (1) Depending on the DCLK-to-DATA[] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA[] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.



If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio – 1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host**Notes to Figure 11:**

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM} .
- (2) You can leave the nCEO pin unconnected or use it as a user I/O pin when it does not feed another device's nCE pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP ×8, use DATA[7..0]. If you use FPP ×16, use DATA[15..0].

Figure 13. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1 (1), (2)**Notes to Figure 13:**

- (1) Use this timing waveform and parameters when the DCLK-to-DATA [] ratio is >1. To find out the DCLK-to-DATA [] ratio for your system, refer to Table 49 on page 55.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time as specified by the POR delay.
- (4) After power-up, before and during configuration, CONF_DONE is low.
- (5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (6) "r" denotes the DCLK-to-DATA [] ratio. For the DCLK-to-DATA [] ratio based on the decompression and the design security feature enable settings, refer to Table 49 on page 55.
- (7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA [31 . . 0] pins prior to sending the first DCLK rising edge.
- (8) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (9) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1 ⁽¹⁾

Symbol	Parameter	Minimum	Maximum	Units
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	μ s
t_{STATUS}	nSTATUS low pulse width	268	1,506 ⁽²⁾	μ s
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽²⁾	μ s
t_{CF2CK} ⁽⁵⁾	nCONFIG high to first rising edge on DCLK	1,506	—	μ s
t_{ST2CK} ⁽⁵⁾	nSTATUS high to first rising edge of DCLK	2	—	μ s
t_{DSU}	DATA [] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA [] hold time after rising edge on DCLK	$N-1/f_{DCLK}$ ⁽⁵⁾	—	s
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency (FPP $\times 8/\times 16$)	—	125	MHz
	DCLK frequency (FPP $\times 32$)	—	100	MHz
t_R	Input rise time	—	40	ns
t_F	Input fall time	—	40	ns
t_{CD2UM}	CONF_DONE high to user mode ⁽³⁾	175	437	μ s
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	$4 \times$ maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$ ⁽⁴⁾	—	—

Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.
- (5) N is the DCLK-to-DATA ratio and f_{DCLK} is the DCLK frequency the system is operating.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Table 53. AS Timing Parameters for AS ×1 and AS ×4 Configurations in Stratix V Devices ^{(1), (2)} (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t_{CD2UM}	CONF_DONE high to user mode ⁽³⁾	175	437	μs
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$	—	—

Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (2) t_{CF2CD} , t_{CF2ST0} , t_{CFG} , t_{STATUS} , and t_{CF2ST1} timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform ⁽¹⁾**Notes to Figure 15:**

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF_DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 54 lists the PS configuration timing parameters for Stratix V devices.

Table 54. PS Timing Parameters for Stratix V Devices

Symbol	Parameter	Minimum	Maximum	Units
t_{CF2CD}	nCONFIG low to CONF_DONE low	—	600	ns
t_{CF2ST0}	nCONFIG low to nSTATUS low	—	600	ns
t_{CFG}	nCONFIG low pulse width	2	—	μ s
t_{STATUS}	nSTATUS low pulse width	268	1,506 ⁽¹⁾	μ s
t_{CF2ST1}	nCONFIG high to nSTATUS high	—	1,506 ⁽²⁾	μ s
t_{CF2CK} ⁽⁵⁾	nCONFIG high to first rising edge on DCLK	1,506	—	μ s
t_{ST2CK} ⁽⁵⁾	nSTATUS high to first rising edge of DCLK	2	—	μ s
t_{DSU}	DATA [] setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	DATA [] hold time after rising edge on DCLK	0	—	ns
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency	—	125	MHz
t_{CD2UM}	CONF_DONE high to user mode ⁽³⁾	175	437	μ s
t_{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$ ⁽⁴⁾	—	—

Notes to Table 54:

- (1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
- (3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the “Initialization” section.
- (5) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

Table 55. Initialization Clock Source Option and the Maximum Frequency

Initialization Clock Source	Configuration Schemes	Maximum Frequency	Minimum Number of Clock Cycles ⁽¹⁾
Internal Oscillator	AS, PS, FPP	12.5 MHz	8576
CLKUSR	AS, PS, FPP ⁽²⁾	125 MHz	
DCLK	PS, FPP	125 MHz	

Notes to Table 55:

- (1) The minimum number of clock cycles required for device initialization.
- (2) To enable CLKUSR as the initialization clock source, turn on the **Enable user-supplied start-up clock (CLKUSR)** option in the Quartus II software from the **General** panel of the **Device and Pin Options** dialog box.

Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G H I	—	—
J	JTAG Timing Specifications	<p>High-speed I/O block—Deserialization factor (width of parallel data bus).</p> <p>JTAG Timing Specifications:</p> 
K L M N O	—	—
P	PLL Specifications	<p>Diagram of PLL Specifications ⁽¹⁾</p>  <p>Note: (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.</p>
Q	—	—
R	R _L	Receiver differential input discrete resistor (external to the Stratix V device).

Table 60. Glossary (Part 3 of 4)

Letter	Subject	Definitions
S	SW (sampling window)	<p>Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown:</p> 
	Single-ended voltage referenced I/O standard	<p>The JEDEC standard for SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.</p> <p>The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing:</p> <p><i>Single-Ended Voltage Referenced I/O Standard</i></p> 
T	t_c	High-speed receiver and transmitter input and output clock period.
	TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under SW in this table).
	t_{DUTY}	<p>High-speed I/O block—Duty cycle on the high-speed transmitter output clock.</p> <p>Timing Unit Interval (TUI)</p> <p>The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = $1/(\text{receiver input clock frequency multiplication factor}) = t_c/w$)</p>
	t_{FALL}	Signal high-to-low transition time (80-20%)
	t_{INCCJ}	Cycle-to-cycle jitter tolerance on the PLL clock input.
	t_{OUTPJ_IO}	Period jitter on the general purpose I/O driven by a PLL.
	t_{OUTPJ_DC}	Period jitter on the dedicated clock output driven by a PLL.
	t_{RISE}	Signal low-to-high transition time (20-80%)
U	—	—